PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
ISAO KATASHO	05/15/2014
TETSUO OHASHI	05/15/2014

RECEIVING PARTY DATA

Name:	SHIMADZU CORPORATION	
Street Address:	1, NISHINOKYO-KUWABARACHO, NAKAGYO-KU, KYOTO-SHI,	
City:	куото	
State/Country:	JAPAN	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14365104

CORRESPONDENCE DATA

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Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

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Correspondent Name: JIANQ CHYUN INTELLECTUAL PROPERTY OFFICE

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ATTORNEY DOCKET NUMBER:	51073-US-372-PCT
NAME OF SUBMITTER:	BELINDA LEE
SIGNATURE:	/Belinda Lee/
DATE SIGNED:	06/20/2014

Total Attachments: 2

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PATENT 502859962 REEL: 033144 FRAME: 0368

ASSIGNMENT

WHEREAS,

1. ISAO KATASHO

2. TETSUO OHASHI

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title:

CHIP DEVICE FOR MANIPULATING OBJECT COMPONENT, AND

METHOD USING THE SAME

[] Filed: Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, SHIMADZU CORPORATION

of 1, NISHINOKYO-KUWABARACHO, NAKAGYO-KU, KYOTO-SHI, KYOTO, JAPAN

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Date: 15 / May, 2014

Signature: Usav Katashu

Sole or First Joint Inventor: ISAO KATASHO

Signature: Tetsuo Ohashi

Sole or First Joint Inventor: TETSUO OHASHI

RECORDED: 06/20/2014

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